

TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT SILICON GATE CMOS

## 65,536-WORD BY 16-BIT CMOS STATIC RAM

DESCRIPTION

The TC55V1664BJ/BFT is a 1,048,576 bits high speed static random access memory organized as 65,536 words by 16 bits using CMOS technology, and operated from a single 3.3V supply. Toshiba's CMOS technology and advanced circuit form provide high speed feature.

The TC55V1664BJ/BFT has low power feature with device control using chip enable ( $\overline{CE}$ ), and has output enable ( $\overline{OE}$ ) for fast memory access. Also it allows lower and upper byte access by data byte control ( $\overline{LB}$ ,  $\overline{UB}$ ). The TC55V1664BJ/BFT is suitable for use in cache memory where high speed is required, and high speed strage. All inputs and outputs are directly LVTTL compatible.

The TC55V1664BJ/BFT is packaged in 44-pin plastic SOJ and TSOP with 400 mil width for high density surface assembly.

FEATURES

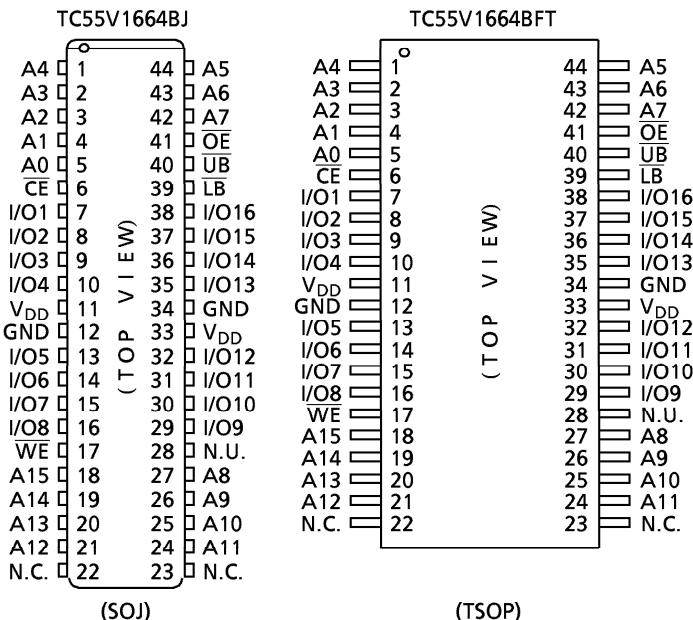
- Fast access time :  
TC55V1664BJ/BFT-8      8ns (MAX)

- Low power dissipation

Cycle Time	8	10	12	15	20	ns
Operation (MAX)	260	230	190	170	150	mA

Standby :                            5mA (MAX)

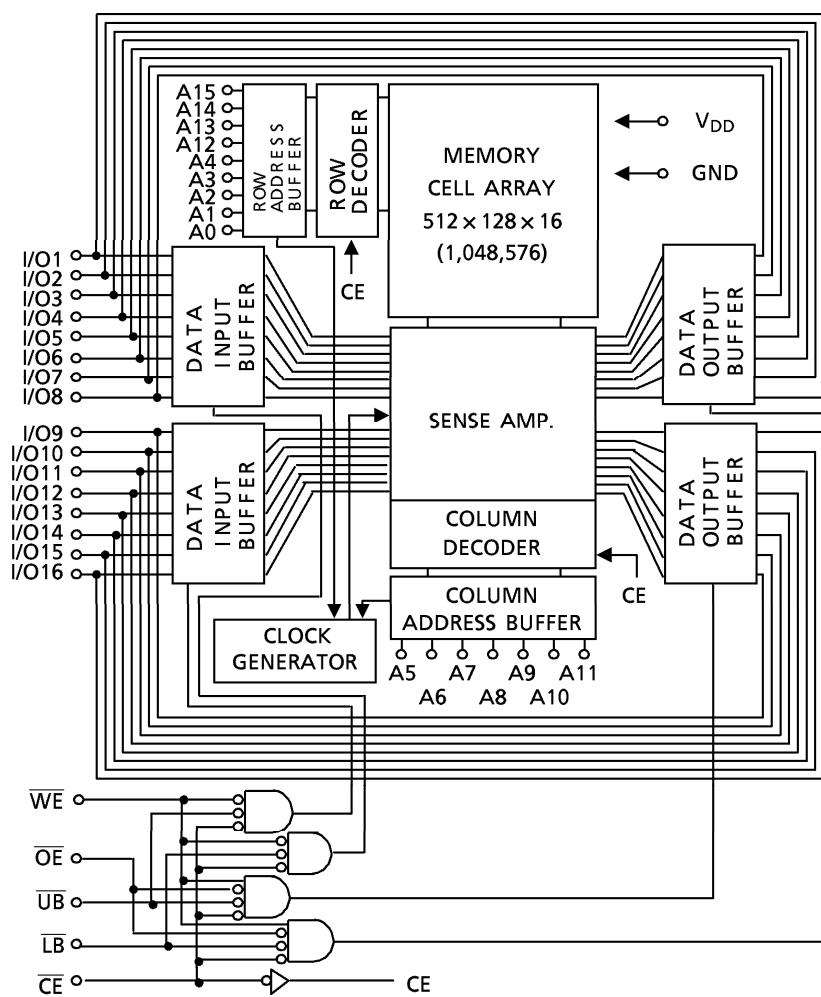
- 3.3V single power supply :  $3.3V \pm 5\%$
- Fully static operation
- All Inputs and Outputs : LVTTL compatible
- Output buffer control :  $\overline{OE}$
- Data byte control  
 $\overline{LB}$  (I/O1 to I/O8),  $\overline{UB}$  (I/O9 to I/O16)
- Package:  
SOJ44-P-400-1.27 (BJ)      (Weight : 1.64gm Typ)  
TSOP II 44-P-400-0.80 (BFT)      (Weight : 0.45gm Typ)

PIN CONNECTIONPIN NAMES

A0 to A15	Address Inputs
I/O1 to I/O16	Data Inputs / Outputs
$\overline{CE}$	Chip Enable Input
WE	Write Enable Input
$\overline{OE}$	Output Enable Input
$\overline{LB}$ , $\overline{UB}$	Data Byte Control Inputs
V <sub>DD</sub>	Power (+ 3.3V)
GND	Ground
N.C.	No Connection
N.U.	Not Usable (Input)

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BLOCK DIAGRAMMAXIMUM RATINGS

SYMBOL	RATING	VALUE	UNIT
$V_{DD}$	Power Supply Voltage	- 0.5 to 4.6	V
$V_{IN}$	Input Terminal Voltage	- 0.5 * to 4.6	V
$V_{I/O}$	Input / Output Terminal Voltage	- 0.5 * to $V_{DD} + 0.5^{**}$	V
$P_D$	Power Dissipation	0.95	W
$T_{solder}$	Soldering Temperature (10s)	260	°C
$T_{strg}$	Storage Temperature	- 65 to 150	°C
$T_{opr}$	Operating Temperature	- 10 to 85	°C

\* : -1.5V with a pulse width of  $20\% \cdot t_{RC}$  min (4ns max)

\*\* :  $V_{DD} + 1.5V$  with a pulse width of  $20\% \cdot t_{RC}$  min (4ns max)

DC RECOMMENDED OPERATING CONDITIONS (Ta = 0° to 70°C)

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT
V <sub>DD</sub>	Power Supply Voltage	3.135	3.3	3.465	V
V <sub>IH</sub>	Input High Voltage	2.0	-	V <sub>DD</sub> + 0.3**	V
V <sub>IL</sub>	Input Low Voltage	- 0.3 *	-	0.8	V

\*: -1.0V with a pulse width of 20% · t<sub>RC</sub> min (4ns max)\*\*: V<sub>DD</sub> + 1.0V with a pulse width of 20% · t<sub>RC</sub> min (4ns max)DC and OPERATING CHARACTERISTICS (Ta = 0° to 70°C, V<sub>DD</sub> = 3.3V ± 5%)

SYMBOL	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
I <sub>IL</sub>	Input Leakage Current (Except NU pin)	V <sub>IN</sub> = 0 to V <sub>DD</sub>	- 1	-	1	µA
I <sub>LO</sub>	Output Leakage Current	$\overline{CE} = V_{IH}$ or $\overline{WE} = V_{IL}$ or $\overline{OE} = V_{IH}$ V <sub>OUT</sub> = 0 to V <sub>DD</sub>	- 1	-	1	µA
I <sub>I(NU)</sub>	Input Current (NU pin)	V <sub>IN</sub> = 0 to 0.8V	- 1	-	20	µA
		V <sub>IN</sub> = 0 to 0.2V	- 1	-	1	
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = - 2mA	2.4	-	-	V
		I <sub>OH</sub> = - 100µA	V <sub>DD</sub> - 0.2	-	-	
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2mA	-	-	0.4	
		I <sub>OL</sub> = 100µA	-	-	0.2	
I <sub>DDO</sub>	Operating Current	tcycle = 8ns	-	-	260	mA
		tcycle = 10ns	-	-	230	
		tcycle = 12ns	-	-	190	
		tcycle = 15ns	-	-	170	
		tcycle = 20ns	-	-	150	
I <sub>DDS1</sub>	Standby Current	$\overline{CE} = V_{IH}$ , Other Inputs = V <sub>IH</sub> / V <sub>IL</sub>	-	-	50	mA
I <sub>DDS2</sub>		$\overline{CE} = V_{DD} - 0.2V$ Other Inputs = V <sub>DD</sub> - 0.2V or 0.2V	-	-	5	

CAPACITANCE (Ta = 25°C, f = 1.0MHz)

SYMBOL	PARAMETER	TEST CONDITION	MAX	UNIT
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = GND	6	pF
C <sub>I/O</sub>	Input/Output Capacitance	V <sub>I/O</sub> = GND	8	pF

NOTE : This parameter is periodically sampled and is not 100% tested.

OPERATING MODE

MODE	<u>CE</u>	<u>OE</u>	<u>WE</u>	<u>LB</u>	<u>UB</u>	I/O1 to I/O8	I/O9 to I/O16	POWER
Read	L	L	H	L	L	Output	Output	$I_{DDO}$
				H	L	High Impedance	Output	$I_{DDO}$
				L	H	Output	High Impedance	$I_{DDO}$
Write	L	X	L	L	L	Input	Input	$I_{DDO}$
				H	L	High Impedance	Input	$I_{DDO}$
				L	H	Input	High Impedance	$I_{DDO}$
Outputs Disable	L	H	H	X	X	High Impedance	High Impedance	$I_{DDO}$
	L	X	X	H	H			
Standby	H	X	X	X	X	High Impedance	High Impedance	$I_{DDS}$

X : H or L

NOTE : N.U. pin must be kept open electrically or pulled down to GND level or less than 0.8V.  
 Applying a voltage more than 0.8V to N.U. pin is prohibited.

AC CHARACTERISTICS (Ta = 0° to 70°C<sup>(1)</sup>, V<sub>DD</sub> = 3.3V ± 5%)

## READ CYCLE

SYMBOL	PARAMETER	TC55V1664BJ/BFT-8		UNIT
		MIN	MAX	
t <sub>RC</sub>	Read Cycle Time	8	-	ns
t <sub>ACC</sub>	Address Access Time	-	8	
t <sub>CO</sub>	$\overline{CE}$ Access Time	-	8	
t <sub>OE</sub>	$\overline{OE}$ Access Time	-	4	
t <sub>BA</sub>	$\overline{UB}, \overline{LB}$ Access Time	-	4	
t <sub>OH</sub>	Output Data Hold Time from Address Change	3	-	
t <sub>COE</sub>	Output Enable Time from $\overline{CE}$	3	-	
t <sub>OE</sub>	Output Enable Time from $\overline{OE}$	1	-	
t <sub>BE</sub>	Output Enable Time from $\overline{UB}, \overline{LB}$	1	-	
t <sub>COD</sub>	Output Disable Time from $\overline{CE}$	-	5	
t <sub>ODO</sub>	Output Disable Time from $\overline{OE}$	-	5	
t <sub>BOD</sub>	Output Disable Time from $\overline{UB}, \overline{LB}$	-	5	

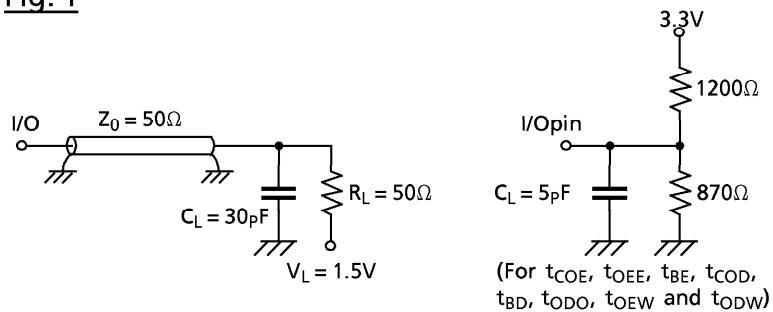
## WRITE CYCLE

SYMBOL	PARAMETER	TC55V1664BJ/BFT-8		UNIT
		MIN	MAX	
t <sub>WC</sub>	Write Cycle Time	8	-	ns
t <sub>WP</sub>	Write Pulse Width	6	-	
t <sub>CW</sub>	Chip Enable to End of Write	7	-	
t <sub>BW</sub>	$\overline{UB}, \overline{LB}$ Enable to End of Write	7	-	
t <sub>AW</sub>	Address Valid to End of Write	7	-	
t <sub>AS</sub>	Address Set Up Time	0	-	
t <sub>WR</sub>	Write Recovery Time	0	-	
t <sub>DS</sub>	Data Set Up Time	5	-	
t <sub>DH</sub>	Data Hold Time	0	-	
t <sub>OEW</sub>	Output Enable Time from $\overline{WE}$	1	-	
t <sub>ODW</sub>	Output Disable Time from $\overline{WE}$	-	5	

## AC TEST CONDITIONS

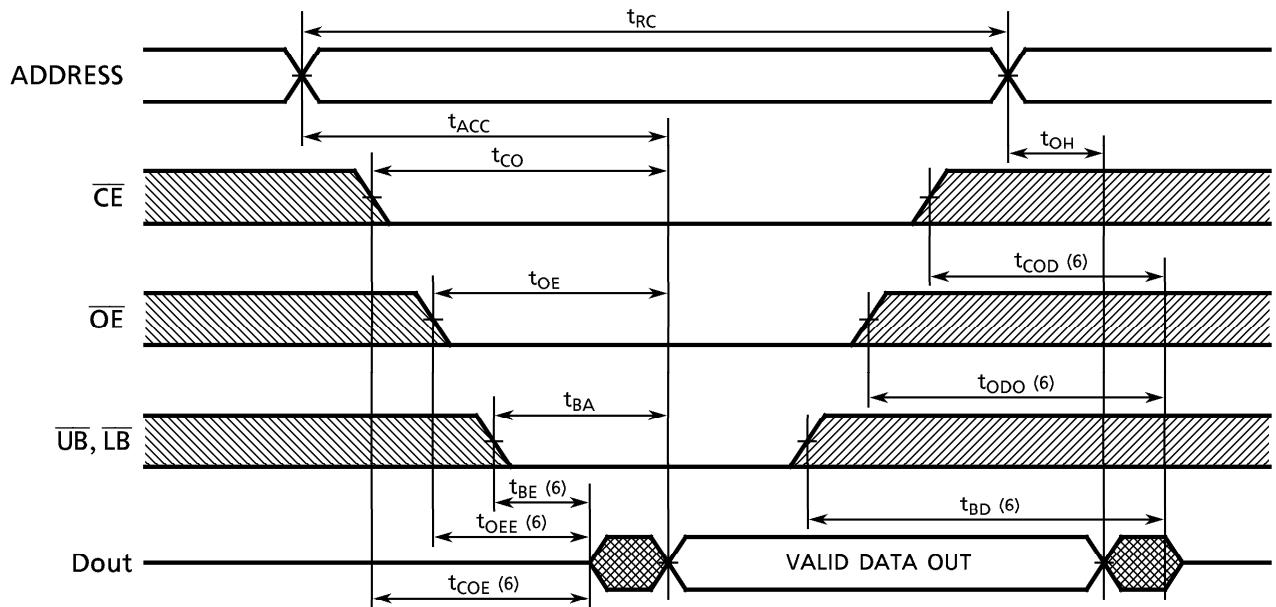
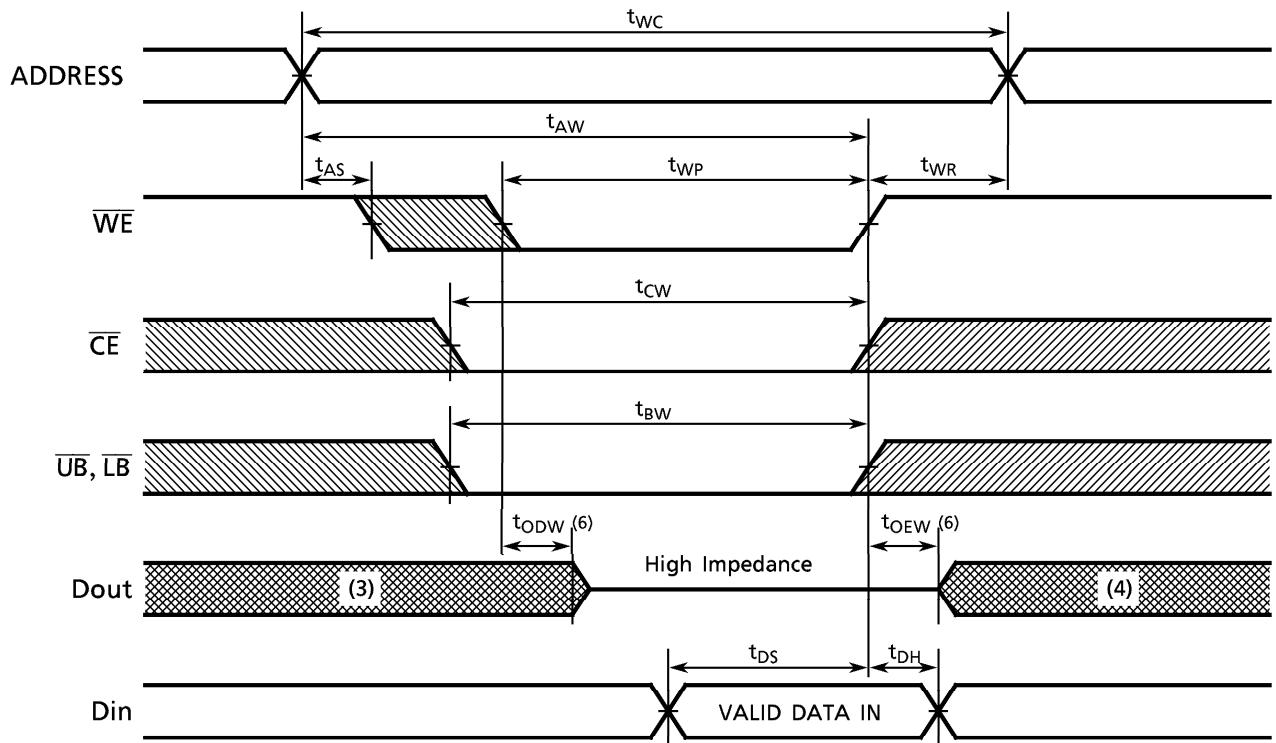
Fig. 1

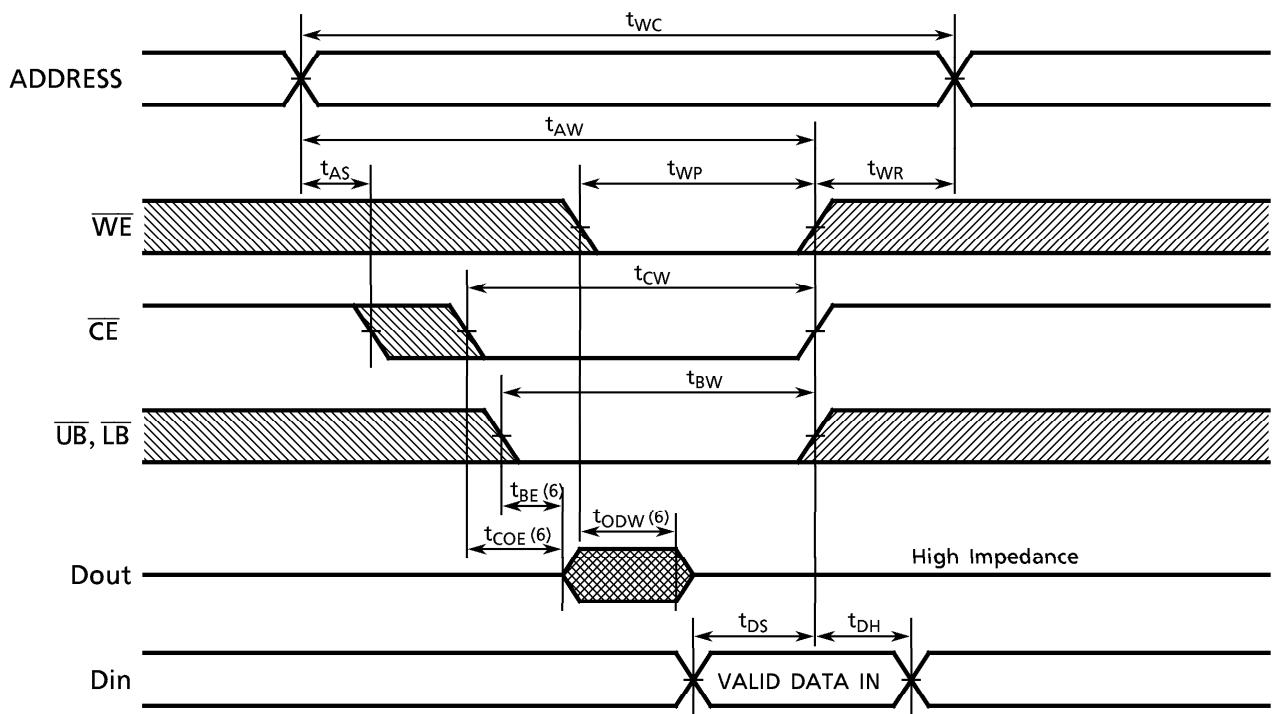
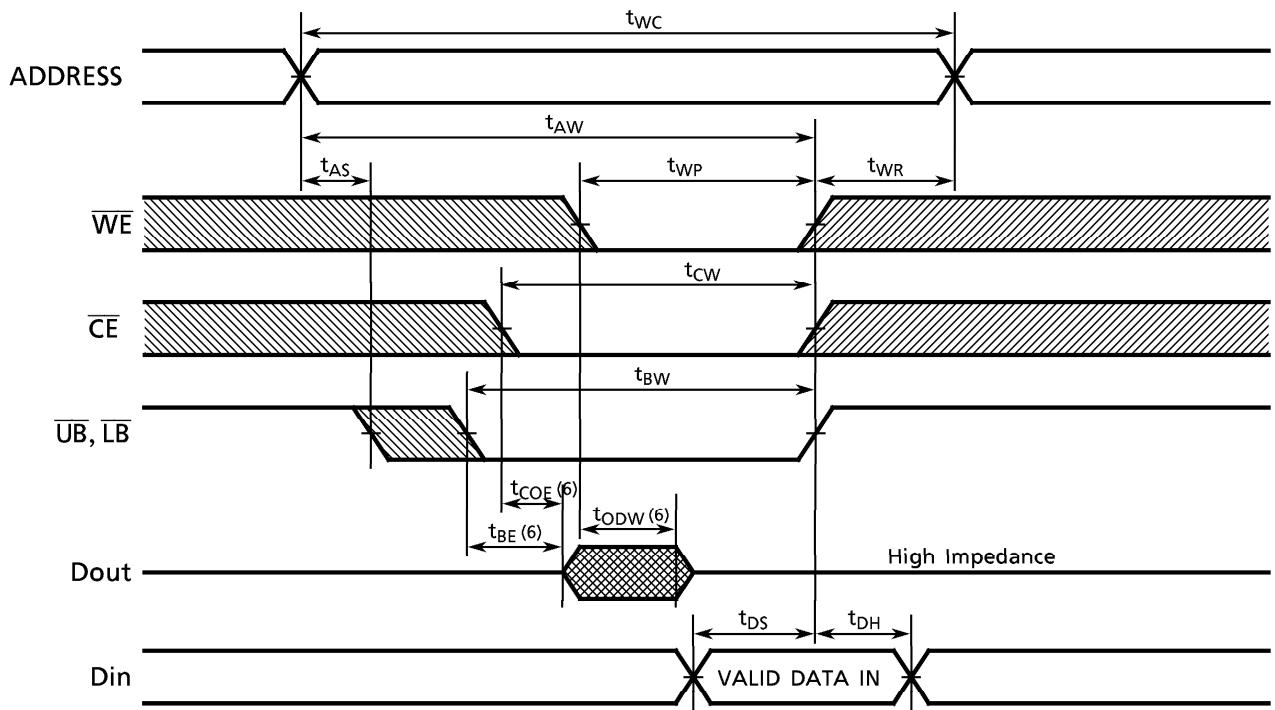
Input Pulse Level	3.0V/0.0V
Input Pulse Rise and Fall Time	2ns
Input Timing Measurement Reference Level	1.5V
Output Timing Measurement Reference Level	1.5V
Output Load	Fig. 1



TIMING WAVEFORMS

READ CYCLE (2)

WRITE CYCLE 1 (5) ( $\overline{WE}$  Controlled)

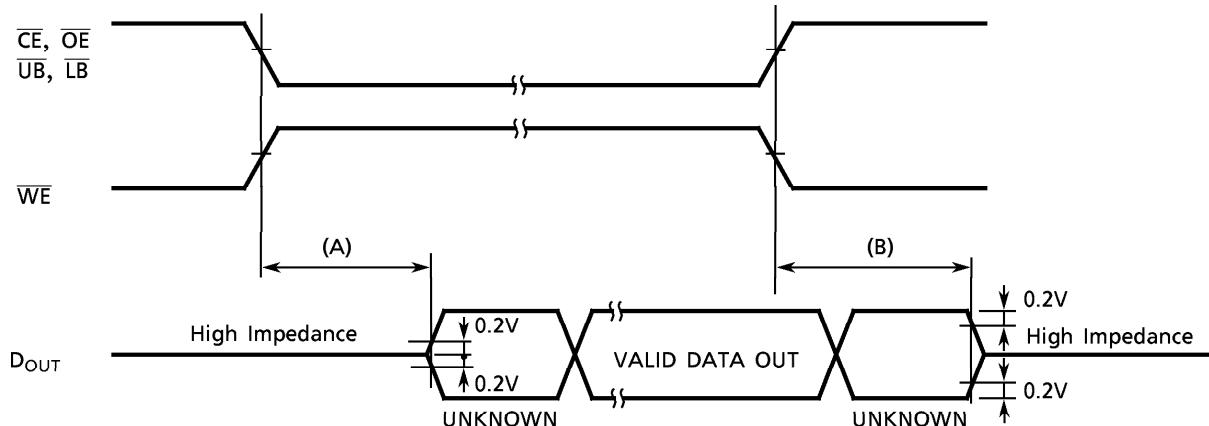
WRITE CYCLE 2 (5) ( $\overline{CE}$  Controlled)WRITE CYCLE 3 (5) ( $\overline{UB}$ ,  $\overline{LB}$  Controlled)

## NOTE :

1. The operating temperature ( $T_a$ ) is guaranteed with transverse air flow exceeding 400 linear feet per minute.
2.  $\overline{WE}$  is High for Read Cycle.
3. Assuming that  $\overline{CE}$  Low transition occurs coincident with or after  $\overline{WE}$  Low transition, Outputs remain in a high impedance state.
4. Assuming that  $\overline{CE}$  High transition occurs coincident with or prior  $\overline{WE}$  High transition, Outputs remain in a high impedance state.
5. Assuming that  $\overline{OE}$  is High for Write Cycle, Outputs are in a high impedance state during this period.
6. These parameters are specified as follows and measured by using the load shown in Fig. 1.

(A)  $t_{COE}, t_{OE}, t_{BE}, t_{EW}$  ..... Output Enable Time

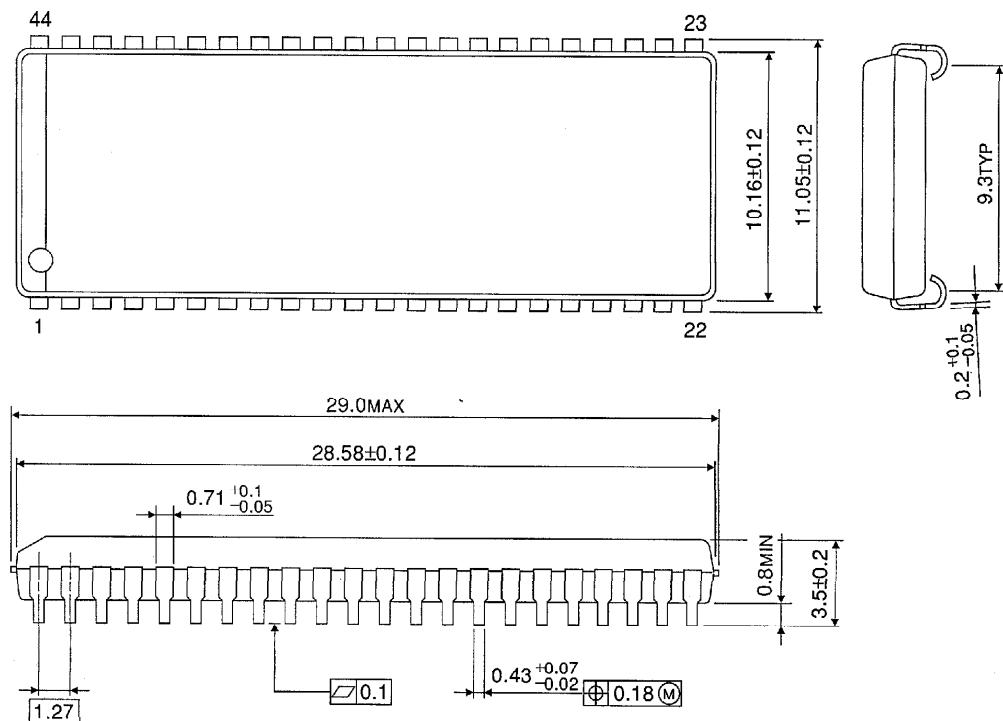
(B)  $t_{COD}, t_{ODO}, t_{BD}, t_{DW}$  ..... Output Disable Time



PACKAGE DIMENSIONS

Plastic SOJ (SOJ44-P-400-1.27)

Unit in mm

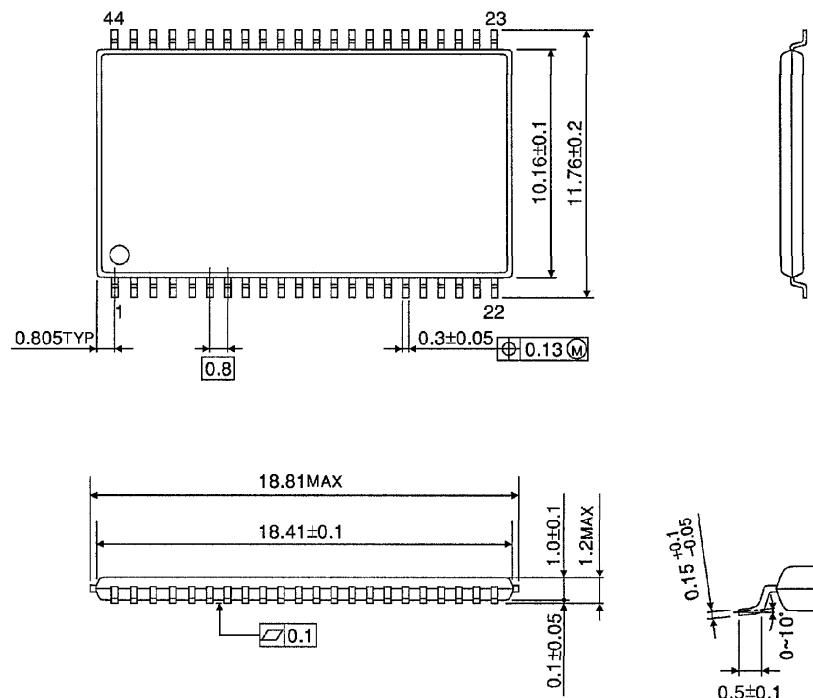


Weight : 1.64g (Typ)

PACKAGE DIMENSIONS

Plastic TSOP (TSOPII 44-P-400-0.80)

Unit in mm



Weight : 0.45g (Typ)